

Appl. No. 10/709,663
Amdt. dated April 28, 2005
Reply to Office action of February 01, 2005

Amendments to the Claims

1. (previously presented) A method for manufacturing a light emitting diode having a transparent substrate, the method comprising:
forming a semiconductor multilayer on a first substrate producing a first
5 multilayer structure;
forming a conductive amorphous interface layer on a second substrate, the second substrate being transparent in nature, producing a second multilayer structure;
bonding the first multilayer structure to the second multilayer structure, producing
a third multilayer structure; and
10 removing the first substrate from the third multilayer structure.
2. (original) The method of claim 1 further comprising a step of forming a transparent conductive layer on the third multilayer structure after removing the first substrate.
- 15 3. (previously presented) The method of claim 1, wherein the amorphous interface layer is made of at least one selected from a group consisting of indium tin oxide, indium cadmium oxide, antimony tin oxide, and transparent adhesive agent.
- 20 4. (previously presented) A method for manufacturing a light emitting diode, comprising:
forming a semiconductor multilayer on a first substrate producing a first
multilayer structure;
forming a conductive amorphous interface layer on a second substrate, the second
substrate being transparent in nature, producing a second multilayer structure;
25 bonding the first multilayer structure to the second multilayer structure, producing
a third multilayer structure; and
removing the first substrate from the third multilayer structure.

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5. (original) The method of claim 4 further comprising a step of forming a transparent
conductive layer on the third multilayer structure after removing the first substrate.
6. (previously presented) The method of claim 4, wherein the amorphous interface layer
5 is made of at least one selected from a group consisting of indium tin oxide, cadmium
tin oxide, antimony tin oxide, and transparent adhesive agent.
7. (new) The method of claim 1 further comprising etching away a portion of the first
multilayer structure to partially expose the amorphous interface layer.

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